

LINEAR TECHNOLOGY MATERIALS DECLARATION

1t3015mpmse-2.5#trpbf

(Engineering Calculation)

MSOP-Exposed

(printed on: 2020-07-11 17:23:13)

TOTAL MASS (g) : 0.03724

| COMPONENT MATERIAL | VENDOR/ INDUSTRY NAMES | CONSTITUENT NAME | CAS NUMBER | CONSTITUENT MASS (g) | CONSTITUENT (PPM) OF MATERIAL | CONSTITUENT (PPM) OF TOTAL PKG. | | |
|--------------------------------|----------------------------------|--------------------------------|------------|----------------------|-------------------------------|---------------------------------|----------------|----------------------|
| Active Device | Linear Technology | Silicon (Si) | 7440-21-3 | 0.002740 | 1000000 | 73576.75 | | |
| Die Coat | Dow Corning | Silicone | 69430-27-9 | 0.000000 | 0 | 0 | | |
| Lead Frame | Cu | Copper (Cu) | 7440-50-8 | 0.013845 | 975000 | 371777.40625 | | |
| | | Iron (Fe) | 7439-89-6 | 0.000341 | 24000 | 9156.81445312 | | |
| | | Phosphorus (P) | 7723-14-0 | 0.000004 | 300 | 107.411315918 | | |
| | | Zinc (Zn) | 7440-66-6 | 0.000010 | 700 | 268.528259277 | | |
| | | Nickel (Ni) | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Silicon (Si) | 7440-21-3 | 0.000000 | 0 | 0 | | |
| | | Magnesium (Mg) | 7439-95-4 | 0.000000 | 0 | 0 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| Lead Frame Total: | | | | 0.014200 | 1000000 | 381310.15625 | | |
| Plating | PMI | Exter. Plating Pb | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Exter. Plating Sn | 7440-31-5 | 0.000710 | 1000000 | 19066.1796875 | | |
| | | External Plating Total: | | | | 0.000710 | 1000000 | 19066.1796875 |
| | | Inter. Plating Ni | 7440-02-0 | 0.000000 | 0 | 0 | | |
| | | Inter. Plating Ag | 7440-22-4 | 0.000086 | 1000000 | 2309.34326172 | | |
| Internal Plating Total: | | | | 0.000086 | 1000000 | 2309.34326172 | | |
| Die Attach | ELECTRICALLY CONDUCTIVE ADHESIVE | Silver (Ag) | 7440-22-4 | 0.000423 | 820000 | 11358.7460938 | | |
| | | Tin (Sn) | 7440-31-5 | 0.000000 | 0 | 0 | | |
| | | Lead (Pb) | 7439-92-1 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.000000 | 0 | 0 | | |
| | | Indium (In) | 7440-74-6 | 0.000000 | 0 | 0 | | |
| | | Metal Oxide | | 0.000000 | 0 | 0 | | |
| | | Antimony (Sb) | 7440-36-0 | 0.000000 | 0 | 0 | | |
| | | Resin (EP) | | 0.000093 | 180000 | 2497.31298828 | | |
| Die Attach Total: | | | | 0.000516 | 1000000 | 13856.0585938 | | |
| Encapsulation | MULTI-AROMATIC RESIN Br/Sb FREE | Resin (EP) | | 0.002439 | 130000 | 65494.046875 | | |
| | | Bromine (Br) | 40039-93-8 | 0.000000 | 0 | 0 | | |
| | | Silica (SiO2) | 60676-86-0 | 0.015571 | 830000 | 418125.40625 | | |
| | | Antimony Trioxide (Sb2O3) | 1309-64-4 | 0.000000 | 0 | 0 | | |
| | | Metal Hydroxide | | 0.000657 | 35000 | 17642.3085938 | | |
| | | Carbon Black (C) | 1333-86-4 | 0.000094 | 5000 | 2524.16601562 | | |
| | | Encapsulation Total: | | | | 0.018761 | 1000000 | 503785.90625 |
| Bond Wire Estimated | AFW/TANAKA/ Kn | Gold (Au) | 7440-57-5 | 0.000227 | 1000000 | 6095.59179688 | | |
| | | | | | TOTAL MASS (g) : | 0.03724 | | |